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- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- P-N-P Inputs Reduce DC Loading
- Outputs Have 25-Ω Series Resistor, So No External Resistors are Required
- Package Options Include Plastic "Small Outline" Packages, Plastic and Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

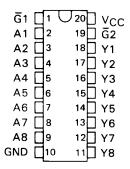
These octal buffers and line drivers are designed to drive capacitive input characteristics of MOS devices and have the performance of the popular SN54ALS240A/SN74ALS240A series. At the same time, they offer a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly enhances printed-circuit-board layout.

The three-state control gate is a 2-input AND with active-low inputs such that if either $\overline{G}1$ or $\overline{G}2$ is high, all eight outputs are in the high-impedance state.

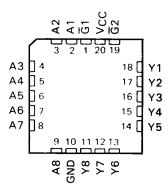
The 'ALS2540 offers inverting data and the 'ALS2541 offers true data at the outputs.

The SN54ALS' is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN74ALS' is characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

SN54ALS2540, SN54ALS2541 . . . J PACKAGE SN74ALS2540, SN74ALS2541 . . . DW OR N PACKAGE (TOP VIEW)

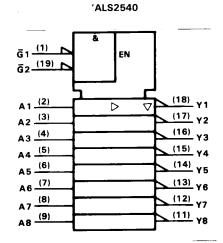


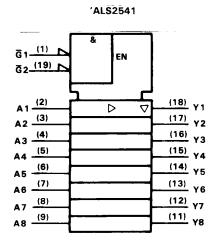
SN54ALS2540, SN54ALS2541 . . . FK PACKAGE (TOP VIEW)



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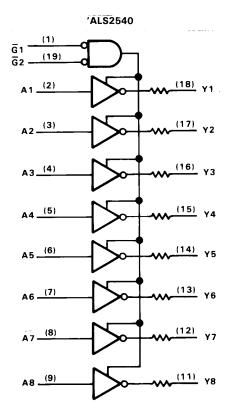
logic symbols†

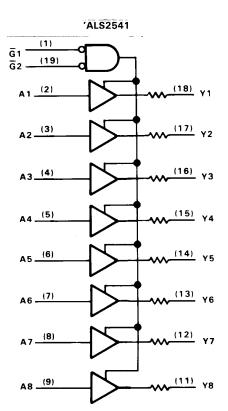




[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)





All output resistors are 25 $\boldsymbol{\Omega}.$

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absolute maximum ratings over operating	ng free-air tem	perature range	(unless othe	rwise noted)
Supply voltage, VCC				7 V
Input voltage				7 V
Voltage applied to a disabled 3-state o	output			5.5 V
Operating free-air temperature range:	SN54ALS2540	SN54ALS254	1	-55°C to 125°C
	SN74ALS2540	SN74ALS254	1	0°C to 70°C
Storage temperature range				-65°C to 150°C

recommended operating conditions

			SN54ALS2540 SN54ALS2541			SN74ALS2540 SN74ALS2541		
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH ,	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
¹ ОН	High-level output current			-0.4			-0.4	mA
^I OL	Low-level output current			12			12	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SI	SN54ALS2540 SN54ALS2541		SN	74ALS2	540	
		TEST COMPLITIONS		SI	V54ALS	2541	SN	74ALS2	541	UNIT
PARAMETER		TEST CONDITIONS			TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK		$V_{CC} = 4.5 V$,	I _I = -18 mA			- 1.2			-1.2	V
Vон		$V_{CC} = 4.5 \text{ V to } 5.5$	$5 \text{ V, I}_{OH} = -0.4 \text{ mA}$	Vcc-	2		Vcc-	2		V
\		V _{CC} = 4.5 V,	I _{OL} = 1 mA		0.15	0.5		0.15	0.5	V
VOL		$V_{CC} = 4.5 \text{ V},$	I _{OL} = 12 mA		0.35	0.8		0.35	0.8] `
lozh		$V_{CC} = 5.5 V$,	$V_0 = 2.7 \text{ V}$			20			20	μΑ
^I OZL		$V_{CC} = 5.5 V$,	$V_0 = 0.4 V$			- 20			- 20	μΑ
ТОН		$V_{CC} = 4.5 \text{ V},$	V ₀ = 2 V	- 15			- 15			mA
TOL		$V_{CC} = 4.5 \text{ V},$	V ₀ = 2 V	30			30			mA
T _I		$V_{CC} = 5.5 V$,	V _I = 7 V			0.1			0.1	mA
ΊΗ		$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
ΊL		V _{CC} = 5.5 V,	V _I = 0.4 V		-	-0.1			-0.1	mA
10‡		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.25 \text{ V}$	- 15		- 70	- 15		- 70	mA
			Outputs high		5	10		5	10	
	'ALS2540	$V_{CC} = 5.5 V$	Outputs low		13	22		13	22	mA
١.			Outputs disabled		11	19		11	19]
Icc			Outputs high		6	14		6	14	
	'ALS2541	$V_{CC} = 5.5 V$	Outputs low		15	25		15	25] mA
			Outputs disabled		13.5	22		13.5	22	



 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

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'ALS2540 switching characteristics (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_L = 50 \text{ pF},$ $R1 = 500 \Omega,$ $R2 = 500 \Omega,$ $T_A = 25 ^{\circ}C$	C _L R1 R2 T _A	$V_{CC} = 4.5 \text{ V to}$ $C_L = 50 \text{ pF},$ $R1 = 500 \Omega,$ $R2 = 500 \Omega,$ $T_A = \text{MIN to N}$ $SN54ALS2540$			UNIT
			'ALS2540			SN74ALS2540		4
			TYP	MIN	MAX	MIN	MAX	
^t PLH	Α	٧	7.5	2	14	2	12	ns
tPHL	ן ^ ו	1	5.6	2	13	2	11] '''
^t PZH	G	V	9	5	18	5	15	ns
^t PZL	7 3 1	1	12.6	8	24	8	20] '''
t _{PHZ}	- G	Y	4	1	12	1	10	ns
, tPLZ	7 '	1	7	2	14	2	12	113

'ALS2541 switching characteristics (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	PUT) $R2 = 500 \Omega, R2 = 500 \Omega, T_A = 25 ^{\circ}C T_A = MIN to MAX$		$C_L = 50 \text{ pF},$ $R1 = 500 \Omega,$ $R2 = 500 \Omega,$ $T_A = MIN \text{ to } M$ $N54ALS2541$ $N = MAX$			UNIT
			'AL\$2541	SN54A	SN54ALS2541 SN74ALS2541			
			TYP	MIN	MAX	MIN	MAX	
tPLH		Y	8.7	2	17	2	15	
tPHL	┥ ^	ĭ	7	2	14	2	12	ns
^t PZH	G		9	5	18	5	15	
^t PZL	7 6 1	ť	12.6	8	24	8	20	ns
tPHZ	- G	Υ	4	1	12	1	10	ns
tPLZ	7 '	1	7	2	14	2	12	113

NOTE 1: Load circuit and voltage waveforms are shown in Section 1.

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS2540N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS2541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

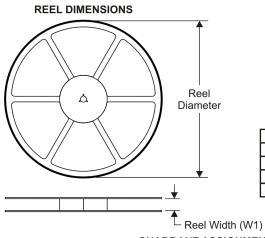
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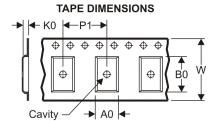
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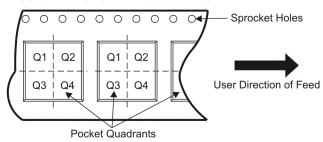
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

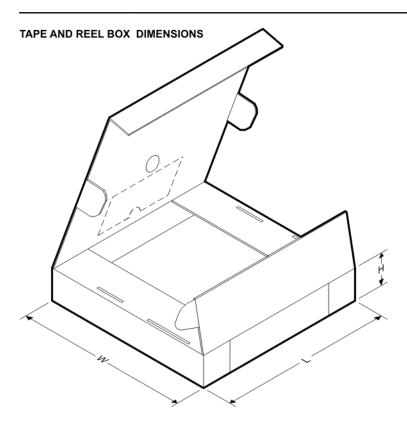


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS2541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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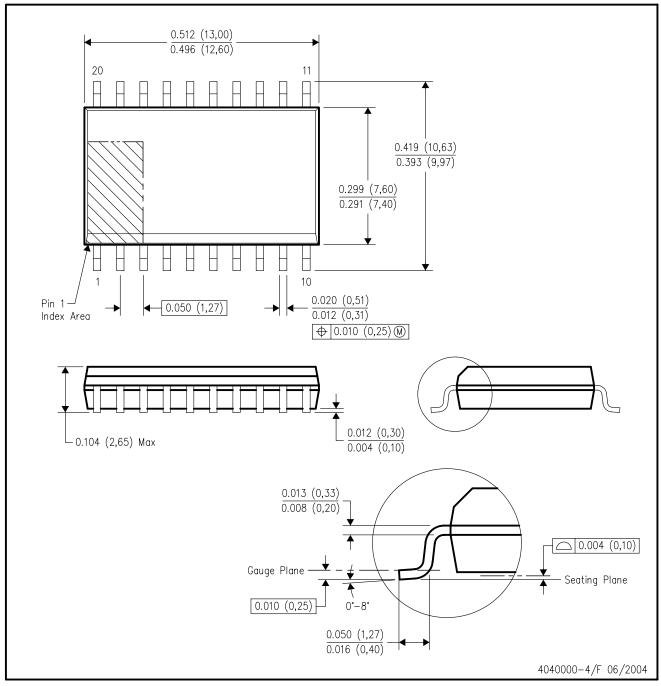


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS2541DWR	SOIC	DW	20	2000	346.0	346.0	41.0

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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